

MA661

Silicon Planar Type (Cathode Common)

Switching

■ Features

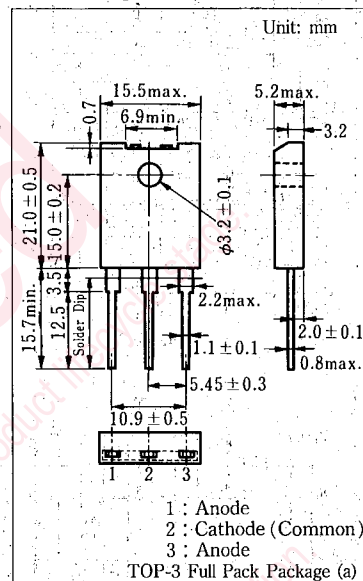
- High V_R
- Low V_F
- Fast t_{rr}

■ Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

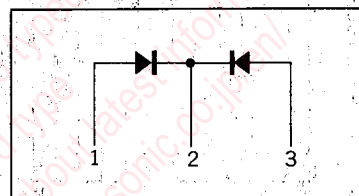
Item	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	200	V
Non-Repetitive Peak Reverse Voltage	V_{RSM}	200	V
Average Forward Current	$I_{F(AV)}$	10	A
Peak Forward Current	I_{FM}	20	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}^*	60	A
Junction Temperature	T_j	$-40 \sim +150$	$^\circ\text{C}$
Storage Temperature	T_{stg}	$-40 \sim +150$	$^\circ\text{C}$

*Sine half wave: 10ms/1 \approx

■ Package Dimensions



■ Inner Circuit

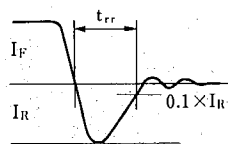
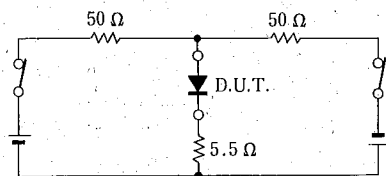


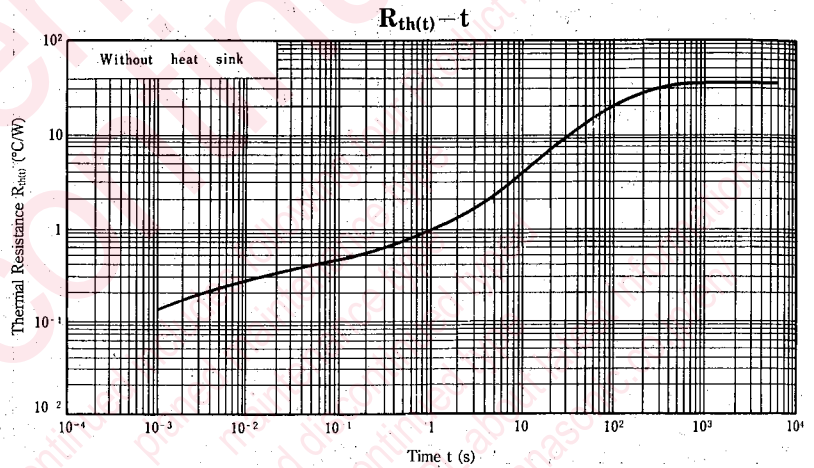
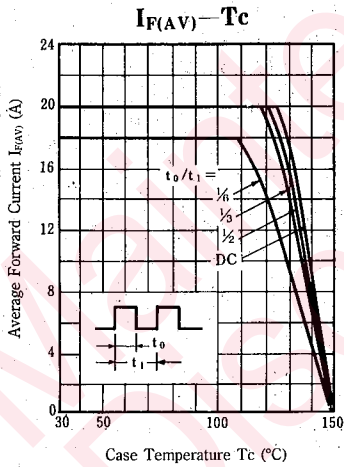
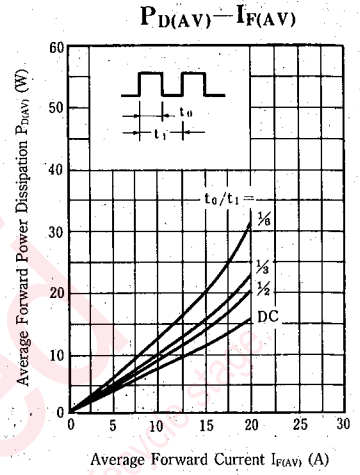
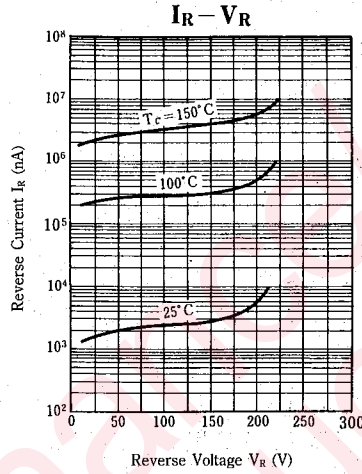
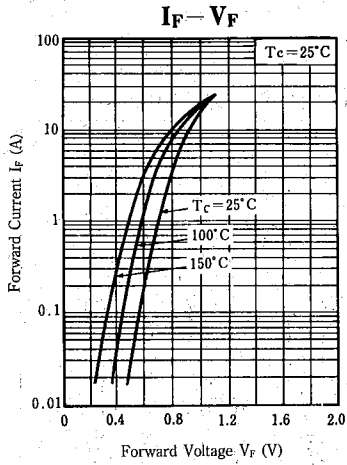
■ Electrical Characteristics ($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	min.	typ.	max.	Unit
Forward Voltage (DC)	V_F	$I_F=5\text{ A}$, $T_c=25^\circ\text{C}$			1	V
Repetitive Peak Reverse Current	I_{RRM1}	$V_{RRM}=200\text{ V}$, $T_c=25^\circ\text{C}$			100	μA
	I_{RRM2}	$V_{RRM}=200\text{ V}$, $T_j=150^\circ\text{C}$			6	mA
Reverse Recovery Time	t_{rr}^*	$I_F=1\text{ A}$, $I_R=1\text{ A}$			100	ns
Thermal Resistance	$R_{th(j-c)}$	Smoothing (CD) between junction and case			2	$^\circ\text{C/W}$
	$R_{th(j-a)}$				40	$^\circ\text{C/W}$

© Input and output frequency of ratings: 10MHz

* t_{rr} measuring circuit





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